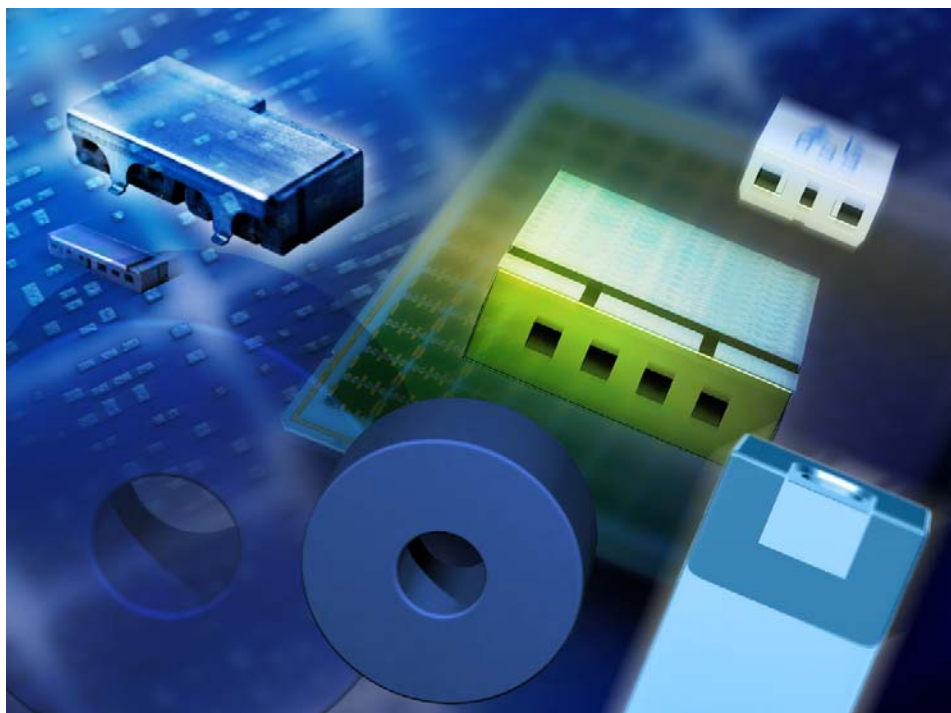


Design Goal

Features

- SMD filter consisting of coupled resonators with stepped impedances
- $\text{MgTiO}_3 - \text{CaTiO}_3$ ($\epsilon_r = 21 / TC_f = 0 \pm 10 \text{ ppm/K}$) with a coating of copper ($10 \mu\text{m}$) and tin ($> 5 \mu\text{m}$)
- Excellent reflow solderability, no migration effect due to copper/tin metallization
- ESD insensitivity and ESD protecting due to filter characteristics

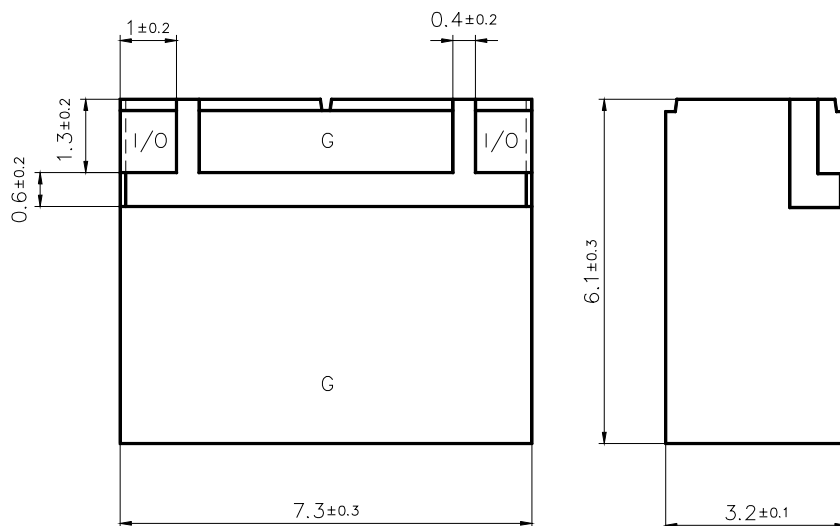
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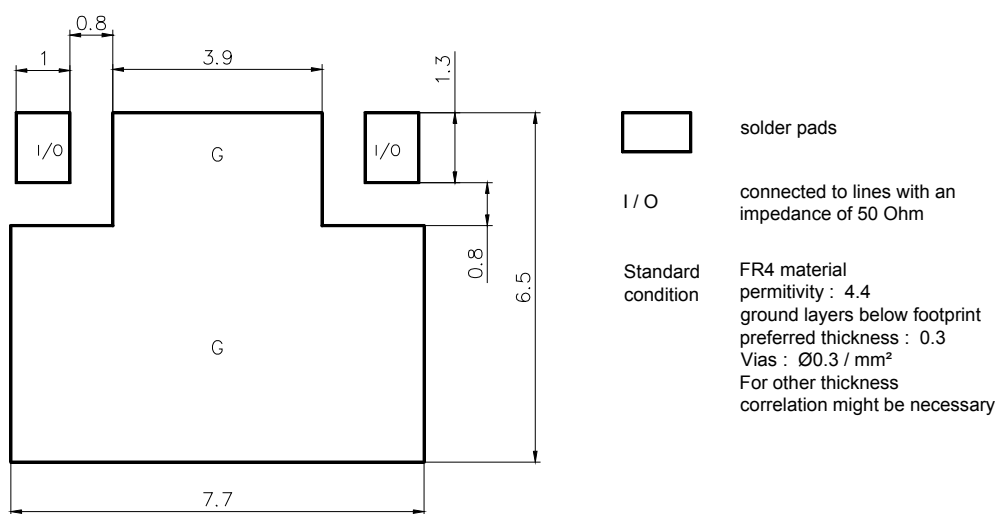
Design Goal

Component drawing



View from below onto the solder terminals and view from beside

Recommended footprint



Design Goal

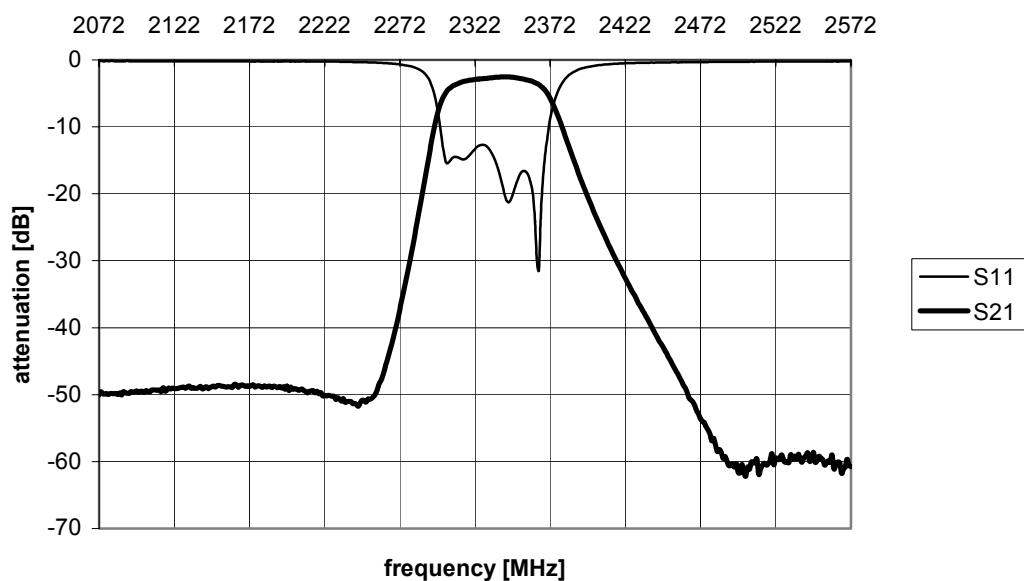
Characteristics

		min.	typ.	max.	
Center frequency	f_c	-	2338.755	-	MHz
Insertion loss	α_{IL}		2.2	2.5	dB
Passband	B	5.5			MHz
Amplitude ripple (peak - peak)	$\Delta\alpha$		0.2	0.5	dB
Standing wave ratio	SWR		1.4	2.0	
Group delay in Passband			15	40	
Impedance	Z		50		Ω
Attenuation	α				
	at 2198.755 ($f_c - 140\text{MHz}$)	45	49		dB
	at 2478.755 ($f_c + 140\text{MHz}$)	50	54		dB

Maximum ratings

EC climatic category (IEC 68-1)		- 40/+ 90/56	
Operating temperature	T_{op}	-20 / +80	°C

Typical passband characteristic



Design Goal

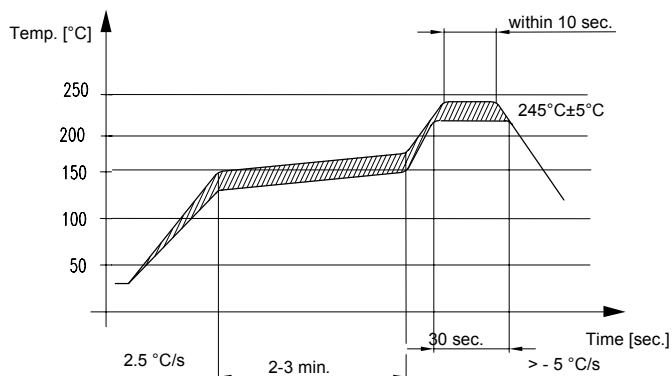
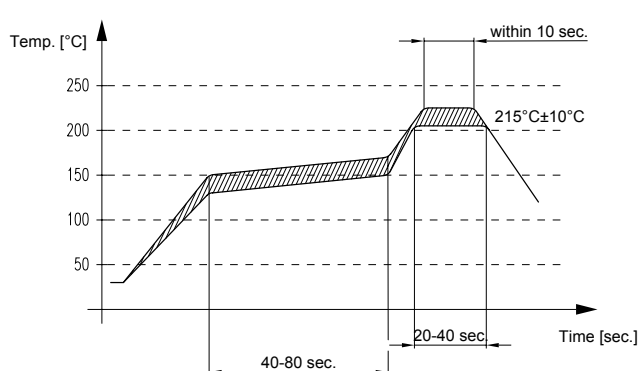
Processing information

- Wettability acc. to IEC 68-2-58: $\geq 75\%$ (after aging)

Soldering Requirements

	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature	235 (max. 2 sec.)	260 (max. 2 sec.)	°C
(measuring point on top surface of the component)	225 (max. 10 sec.)	250 (max. 10 sec.)	°C

Recommended soldering conditions (infrared):



Delivery mode

- Blister tape acc. to IEC 286-3, polyester, grey
- Pieces/tape: **t.b.d.**



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